

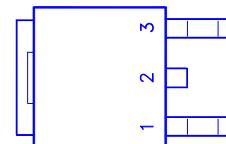
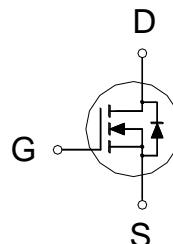
NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
PP4E06BD

TO-252

Halogen-Free & Lead-Free

**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
60V	4.9mΩ	101A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	101	A
	$T_C = 100^\circ\text{C}$		71	
Pulsed Drain Current ¹		I_{DM}	250	A
Avalanche Current		I_{AS}	34	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	59	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	100	W
	$T_C = 100^\circ\text{C}$		50	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	2	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			100	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5\text{V}, I_D = 10\text{A}$		6.3	8	$\text{m}\Omega$
		$V_{GS} = 10\text{V}, I_D = 10\text{A}$		4	4.9	

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Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 10A$		52		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 30V, f = 1MHz$		2252		pF
Output Capacitance	C_{oss}			1141		
Reverse Transfer Capacitance	C_{rss}			37		
Gate Resistance	R_g		$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	0.6		Ω
Total Gate Charge ²	$Q_{g(VGS=10V)}$	$V_{DS} = 30V, I_D = 10A$		35		nC
	$Q_{g(VGS=4.5V)}$			18		
Gate-Source Charge ²	Q_{gs}			7.2		
Gate-Drain Charge ²	Q_{gd}			5.1		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 30V$ $I_D \approx 10A, V_{GS} = 10V, R_{GEN} = 6\Omega$		13		nS
Rise Time ²	t_r			26		
Turn-Off Delay Time ²	$t_{d(off)}$			36		
Fall Time ²	t_f			50		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S			83		A
Forward Voltage ¹	V_{SD}	$I_F = 10A, V_{GS} = 0V$		1.2		V
Reverse Recovery Time	t_{rr}	$I_F = 10A, dI_F/dt = 100A / \mu S$		38		nS
Reverse Recovery Charge	Q_{rr}			27		nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

NIKO-SEM

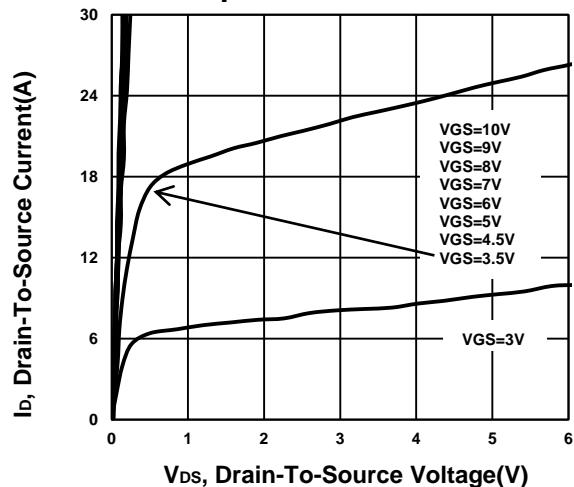
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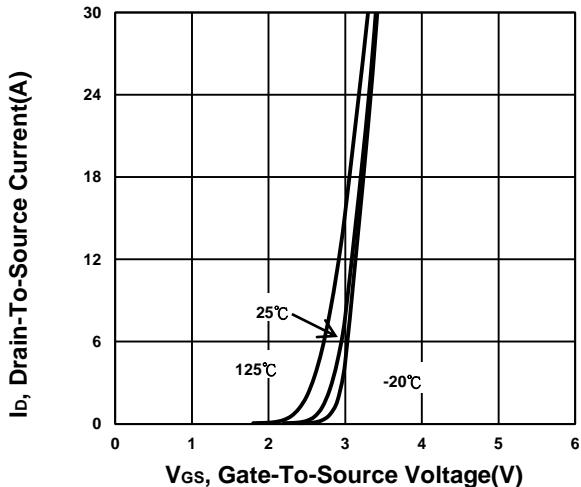
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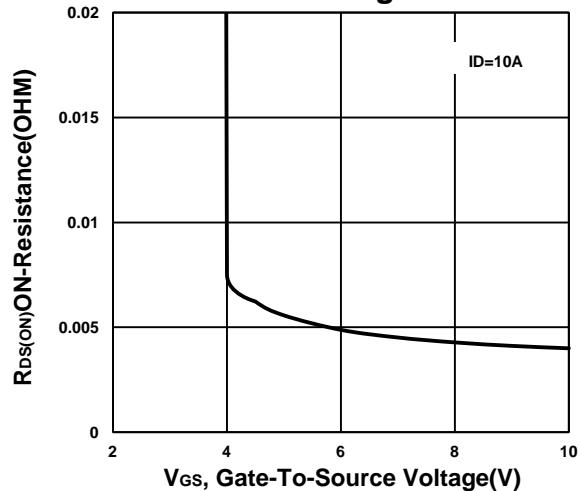
Output Characteristics



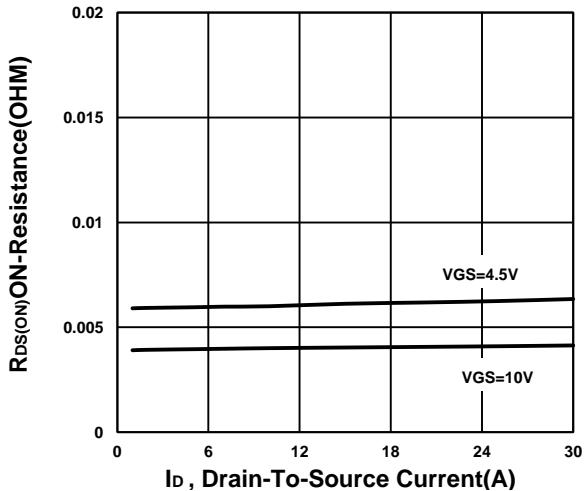
Transfer Characteristics



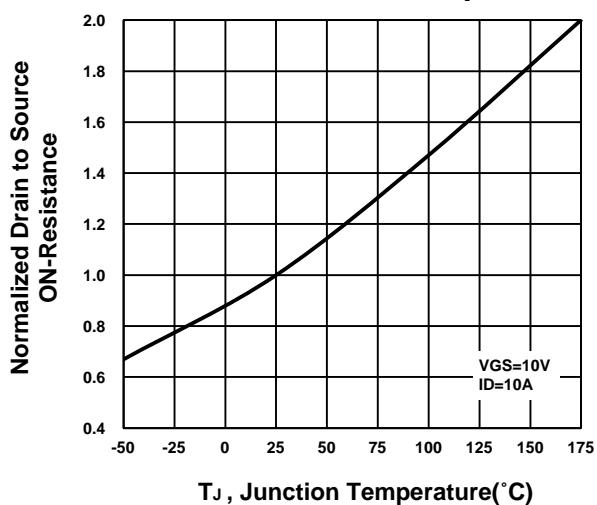
On-Resistance VS Gate-to-Source Voltage



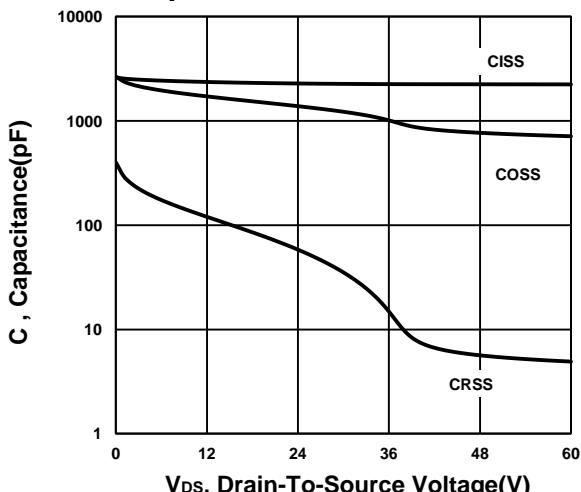
On-Resistance VS Drain Current

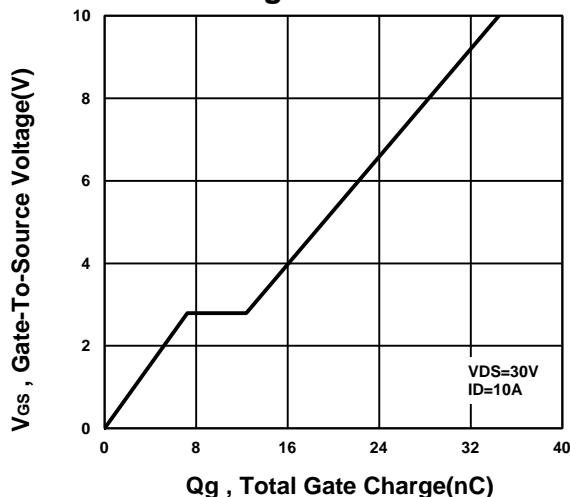
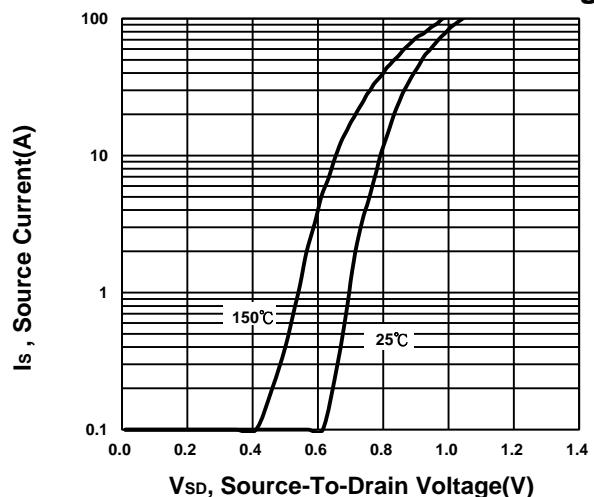
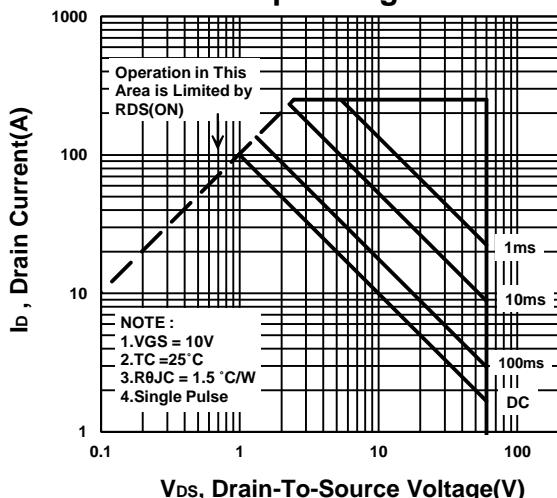
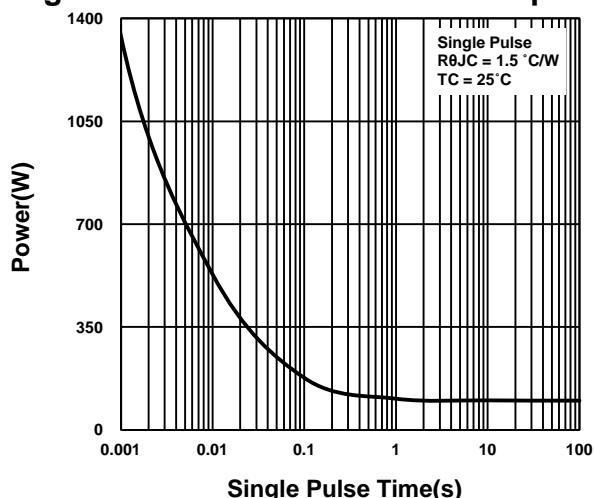


On-Resistance VS Temperature



Capacitance Characteristic



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Halogen-Free & Lead-Free****Gate charge Characteristics****Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**